

REMARKS/ARGUMENTS

Claim 1 has been canceled. Claims 3-8 have been amended to remove multiple dependencies. New claim 9 has been added. Support for the new claim is found at original specification page 9, lines 6-9.

Claim 2 has been amended by replacing “1” with “22.5”. Support for the amendment is found at Embodiments 55 at original specification page 40, lines 8-12. The new low limit of 22.5 wt% is obtained at Embodiments 55 by simply dividing the weight of the HEMA which is the water-soluble polymeric monomer, by the total weight of the dental adhesive composition and converting the resultant ratio to the percentage value.

No new matter has been added. Entry of the amendments and new claims into the record is respectfully requested.

Claims 1-2 and 4-8 are rejected under 35 U.S.C. 102(b) as being anticipated by Nakatsuka (6,512,068). The rejection is respectfully traversed because Nakatsuka does not disclose or teach all the limitations as set forth in the amended claims of the present application.

For anticipation under 35 U.S.C. 102, the reference “must teach every aspect of the claimed invention either explicitly or impliedly.” See MPEP 706.02 Sec.V.

Nakatsuka, however, fails to disclose or teach the water-soluble polymeric monomer of 22.5 to 60 wt% as required in the amended claim 2 of the present application. More specifically, Nakatsuka limits the hydrophilic polymerizable monomer such as HEMA (2-hydroxyethyl methacrylate) to at most 10% by weight. See, e.g., Col. 10, lines 49-61.

If desired, the adhesive composition of the invention may contain a polymerization inhibitor, a colorant, a fluorescent agent, a UV absorbent, etc. Also if desired, a small amount of a hydrophilic polymerizable monomer such as 2-hydroxyethyl methacrylate (HEMA), 3-hydroxypropyl methacrylate or the like may be added to the adhesive composition for the purpose of promoting the dissolution of the polymerization initiator and the hydrophobic polymerizable monomer in the composition. However, the amount of the hydrophilic polymerizable monomer to be in the adhesive composition must be limited to at most 10% by weight, preferably at most 5% by weight of the composition, so as not to lower the bonding durability of the composition. (Emphasis added)

Conversely, Applicants showed that the high adhesive strength and high storage stability were achieved with the HEMA higher than 10 wt%, more specifically, 22.5 wt%. See Embodiments 55 at page 40. Thus, Nakatsuka neither anticipates the claimed invention nor makes it obvious.

Accordingly, withdrawal of this ground of rejection is requested.

Claim 3 is rejected under 35 U.S.C. 103(a) as being unpatentable over Nakatsuka. The rejection is traversed because Nakatsuka does not disclose or teach the limitations as required in the amended claims of the present application.

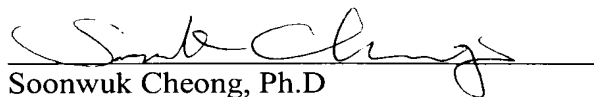
As pointed out above, Nakatsuka limits the hydrophilic polymerizable monomer such as HEMA (2-hydroxyethyl methacrylate) to at most 10% by weight. This disclosure by Nakatsuka teaches away from the use of a water-soluble polymeric monomer higher than 10% by weight. Nakatsuka states that “the amount of the hydrophilic polymerizable monomer to be in the adhesive composition must be limited to at most 10% by weight.” Nakatsuka further indicates that any amount higher will lower the bonding durability of the composition. See, for example, Col. 10, lines 49-61. However, Applicants have found that when using the present composition containing at least 22.5% of a water soluble polymerizable monomer (at least 125% more than permitted by Nakatsuka) the present composition has high adhesive strength and high storage stability.

Therefore, Nakatsuka does not suggest or make obvious Claim 3 dependent from Claim 2. Accordingly, withdrawal of this ground of rejection is requested.

Applicants request allowance of this application.

Respectfully submitted,

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